

CONDITIONAL PETITION FOR EXTENSION OF TIME

If any extension of time for this amendment is required, Applicants request that this be considered a petition therefore. Please charge the required petition fee to Deposit Account No. 14-1263.

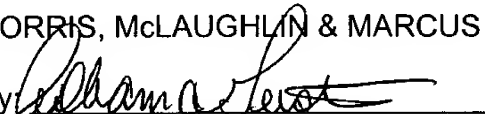
ADDITONAL FEE

Please charge any insufficiency of fee or credit any excess to Deposit Account No. 14-1263.

Respectfully submitted,

NORRIS, McLAUGHLIN & MARCUS

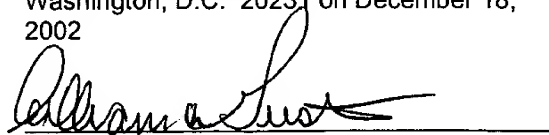
By


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I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail addressed to BOX AF, Assistant Commissioner for Patents, Washington, D.C. 20231 on December 18, 2002



Date: December 18, 2002

**MARKED-UP COPIES OF AMENDED CLAIMS
SHOWING CHANGES RELATIVE TO PREVIOUS VERSIONS**

Claim 14. (twice amended) Thermoplastic adhesive film

comprising

i) a thermoplastic polymer in a proportion of from 30 to 89.9%

by weight,

ii) a) one or more tackifying resins in a proportion of from 5 to 50% by weight or

b) epoxy resins with hardeners, with or without accelerators, in a proportion of from 5 to 40% by weight, or

c) both said one or more tackifying resins in a proportion of from 5 to 50% by weight and said epoxy resins with hardeners, with or without accelerators, in a proportion of from 5 to 40% by weight,

and

iii) silver-coated glass beads in a proportion of from 0.1 to 40% by weight,

iv) where the diameter of the glass beads is at least equal to the thickness of the adhesive film, and

[according to Claim 9,] wherein the adhesive film is in the form of a punched film section.

Claim 15 (twice amended). A method for implanting electrical modules in a card body provided with a cutout for accommodating an electronic module which on [the] a first side has a plurality of contact surfaces and on [the] a second side, which is opposite the first side, has an IC chip whose terminals are connected via electrical conductors to the contact surfaces, wherein [the adhesive film of claim 9]

an electrically conductive, thermoplastic and heat-activatable adhesive film, comprising

i) a thermoplastic polymer in a proportion of from 30 to 89.9% by weight,

ii) a) one or more tackifying resins in a proportion of from 5 to 50% by weight or

b) epoxy resins with hardeners, with or without accelerators, in a proportion of from 5 to 40% by weight, or

c) both said one or more tackifying resins in a proportion of from 5 to 50% by weight and said epoxy resins with hardeners, with or without accelerators, in a proportion of from 5 to 40% by weight,

and

iii) silver-coated glass beads in a proportion of from 0.1 to 40% by weight,

iv) where the diameter of the glass beads is at least equal to the thickness of the adhesive film

is used to connect the second side of the module to the card body.